

#### TIDM-THREEPHASE-BLDC

### **DRV8312 EVALUATION BOARD**



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CH 23, 2011	SHEET 4 OF 6
3312EVM_RevD	DRAWN BY LDN

## **DRV8312 EVALUATION BOARD**

	DESCRIPTION	DAIE	
Α	INITIAL RELEASE	MAY 4, 2010	ML
B	<ol> <li>DELETED OUTA, OUTB, OUTC.</li> <li>ADDED OUTPUT CONNECTOR, TITLED MOTOR.</li> <li>CONNECTED L2-2, L3-2 AND L4-2 TO MOTOR-1,2 AND 3, RESPECTIVELY.</li> <li>DELETED PVDD, GND, +12V AND GND(GND2).</li> <li>ADDED POWER CONNECTOR, VIN.</li> <li>CONNECTED VIN-4 TO C1-1.</li> <li>CONNECTED VIN-2,3 TO GND.</li> <li>CONNECTED VIN-1 TO +12V.</li> <li>ADDED TESTPOINTS TO IA-FB, IB-FB, IC-FB AND I-TOTAL.</li> <li>ADDED 2 PIN HEADERS J2 AND J3 FOR USER POWER ACCESS.</li> <li>CONNECTED J2-1,2 TO +5V AND GND.</li> <li>CONNECTED J3-1,2 TO +3.3V AND GND.</li> <li>CONNECTED J3-1,2 TO +3.3V AND GND.</li> <li>CONNECTED J9-1,2,3 TO +3.3V, J1-7 AND GND, RESPECTIVELY.</li> <li>RENAMED S1 TO RSTA.</li> <li>SWAPPED U1-29 AND U1-30.</li> <li>ADDED SWITCHES, S1 AND S2 TO U1-76 AND U1-78.</li> <li>COPIED DAC1 CIRCUIT, CALLED DAC3, AND CONNECTED TO J1-28.</li> <li>CHANGED R24-R27 TO 33.0K OHMS.</li> <li>CHANGED R48, R49, R54 AND R55 TO 49.9K OHMS.</li> <li>ADDED ISOLATION CIRCUITS.</li> <li>ADDED 12V CONNECTOR, J9.</li> <li>CHANGED C4 TO 22UFD/100V.</li> <li>CHANGED C5 AND C6 TO 100V.</li> </ol>	MARCH 23, 2011	RK

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DESIGN LEAD	RYAN KEHR	EDGE # 6517813	FILENAME	DRV8

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